

## Handling Instructions

### EE895 Miniature Sensor Module for CO<sub>2</sub>, Temperature and Barometric Pressure

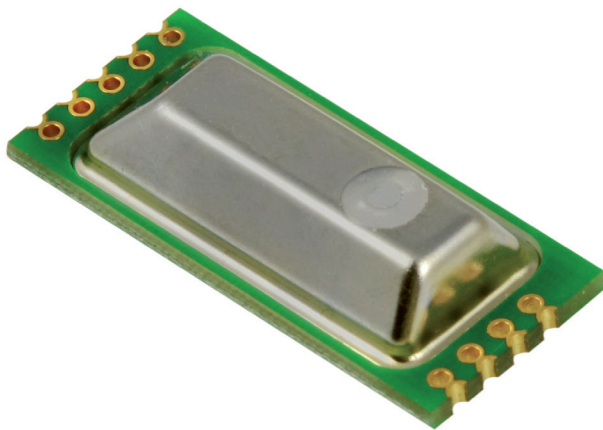
#### Overview

This document gives a recommendation for the general handling regarding transport, storage and assembly process of the EE895.

The miniature sensor module is a measuring element for CO<sub>2</sub>, temperature and barometric pressure.

Therefore, special care in handling is necessary during assembly and further transport.

The physical properties of the miniature sensor module can change due to mechanical or thermal loads, high acceleration or mechanical shock. This may have an influence on the adjustment carried out at the factory and can lead to incorrect measurements. In extreme cases, the module can get harmed.



EE895 Module



EE895 50 pcs. Tray Packaging

#### Storage Conditions

Please observe the following ambient conditions for storage:

Temperature: -40...60 °C (-40...140 °F)

Humidity: 0...95 %RH (non-condensing)

Pressure: 700...1100 mbar (10...20 psi)

#### Moisture Sensitivity Level Rate

The EE895 is not intended for reflow soldering and consequently it does not feature a moisture sensitivity level rate (MSL). Nevertheless, it is to be considered compatible with MSL 1 for storage and handling.

#### ESD Protection



ESD precautions shall be observed while manually soldering the EE895.

The EE895 can be mounted facing either upwards or downwards.

Further details on hand soldering in the variants solder pads or plated contacts are described in the "Mounting Recommendation" section of the User Manual.

## Mechanical Stress

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### During Transportation:

If the product is removed from the original packaging and the transport container inside, special care must be taken against high acceleration or mechanical shock. Accelerations resulting, e.g. from an impact on the ground can lead to impairment of the measurement results.

Please follow the existing guidelines for product packaging for electronics. This includes special attention to the interior padding, guidelines for product positioning and sealing of the packaging.

### During Mounting:

The EE895 housing and the circuit board shall not be exposed to unnecessary mechanical stress during installation and mounting.

Touching the metal housing should be avoided. It is better to handle the module by its PCB edges.



The sensor module deploys a fine dust filter for sensing module protection. If the EE895 is deployed in a device which is designed for harsh environments, the device shall be equipped with a filter as well.

## Revision History

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Date	Revision number	Changes
May 2021	v1.0	Initial version